# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

[List multiple models if applicable.]

- HP ENVY Notebook PC
- HP ENVY 17 Notebook PC
- HP ENVY m7 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>
Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Remove base rubber foot -L & -R
3. Dis-fasten Base Cap -L & -R screw*4
4. Remove Base Cap foot -L & -R
5. Dis-fasten ODD screw*1
6. Remove ODD
7. Dis-fasten BASE screw*20
8. Pull out FFC*5 (Power, Touchpad, keyboard membrane, keyboard backlight, Fingerprint)
9. Dis-fasten daughter boards screw*6 (Power, Touchpad, Fingerprint)
10. Remove Fingerprint Bkt & Remove daughter boards*3 (Power, Touchpad, Fingerprint)
11. Pull out wire cable*6 (LCD, DC cable, HDD, ODD, speaker, WOOFER) Pull out FFC*2 (USB, Battery)
12. Pull out Antenna cables
13. Dis-fasten Wireless screw*1
14. Remove Wireless card
15. Remove HDD
16. Dis-fasten USB boards screw*2
17. Remove USB boards
18. Dis-fasten motherboard screw*7
19. Remove motherboard
20. Remove Memory
21. Pull out fan cable
22. Dis-fasten Fan screws*1
23. Remove Fan
24. Dis-fasten thermal module screw*7
25. Remove thermal module
26. Remove ODD cable
27. Dis-fasten Battery boards screw*2
28. Remove Battery boards
29. Dis-fasten speaker screw*2
30. Remove speaker -L & -R
31. Dis-fasten woofer screw*3
32. Remove woofer
33. Dis-fasten Hinge screw*7
34. Remove DC cable

PSG instructions for this template are available at [EL-MF877-01](#)
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total

![Total Image]

3.22 Remove battery module and Base Cap -L & -R

![Battery and Base Cap Image]

3.23 Remove ODD module.

![ODD Module Image]
3.24 Remove TOP assy.

3.25 Remove Power boards & Touchpad & Fingerprint BKT & Fingerprint

3.26 Remove Wireless card & HDD & USB boards.
3.27 Remove motherboard & Battery boards & speaker & ODD cable & woofer.

3.28 Remove Memory & thermal module

3.29 Remove LCD bezel
3.30 Remove Panel & Camera module & LCD cable & camera cable & Antenna cables

3.31 Remove Hinge -L & -R